

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 – 3. (Cancelled)

4. (Currently Amended) A print assembly for pagewidth inkjet printing, the print assembly comprising

an elongate carrier that is mountable on a support structure of a printer in an operative position with respect to a platen of the printer;

a number of printhead chips ~~including Micro-Electrical Mechanical Systems (MEMS) incorporating actuator arms that are displaceable to eject ink~~ positioned on the carrier, the printhead chips each having a plurality of ink ejection nozzle arrangements on a wafer substrate, each nozzle arrangement having an actuator for ejecting ink from an associated nozzle when a resistive element of said actuator is heated by an electrical current supplied by drive circuitry on the wafer substrate ~~positioned on the carrier and together defining a printhead that is configured to eject at least one billion drops per second into a printing zone defined between the printhead and the platen of the printer, the printhead chips being each positioned at a common angle of greater than zero degrees and less than ninety degrees with respect to a line extending a length of the printing zone, so that consecutive printhead chips overlap at their ends; and~~

~~control circuitry~~ at least one controller that is also positioned on the carrier and that is configured to control operation of at least 10,000 nozzle arrangements of the printhead chips; ~~and~~

~~a feed mechanism positioned on the support structure for feeding a print medium through the printing zone, the feed mechanism including a media roll for carrying print media to be provided to the printing zone and a take up spool configured to receive printed print media from the printing zone.~~

5. (Cancelled)

6. (Cancelled)

7. (Currently Amended) A print assembly as claimed in ~~claim 6~~claim 4, in which the printhead chips together incorporate at least one hundred thousand nozzle arrangements.
8. (Currently Amended) A print assembly as claimed in ~~claim 7~~claim 4, in which the printhead chips together incorporate at least two hundred thousand nozzle arrangements.
9. (Original) A print assembly as claimed in claim 8, which includes between forty and one hundred printhead chips positioned on the carrier.
10. (Original) A print assembly as claimed in claim 4, in which each printhead chip is the product of an integrated circuit fabrication process.
11. (Currently Amended) A print assembly as claimed in claim 10, in which ~~each printhead chip includes a wafer substrate and~~the drive circuitry is comprised in a CMOS drive circuitry layer positioned on the wafer substrate with the nozzle arrangements positioned on the wafer substrate and the CMOS drive circuitry layer.
12. (Previously Presented) A print assembly as claimed in claim 11, in which each nozzle arrangement is electrically connected to the CMOS drive circuitry layer.
13. (Original) A print assembly as claimed in claim 12, which includes a plurality of printhead modules, each printhead module incorporating a printhead chip, the printhead modules being mounted on the carrier.
- 14-20. (Cancelled)